

LISTING OF THE CLAIMS

The following listing of claims replaces all claim listings and versions in the application:

1. - 9. (Canceled)

10. (Previously Presented) A substrate processing method comprising;

a first step of supplying an alkaline solution to a surface of a substrate;

a second step of supplying an acid solution to the surface of said substrate after said first step; and

a third step of supplying said alkaline solution to the surface of said substrate after said second step;

rotating said substrate in a horizontal plane from said first step to said third step; and

said supplying of said alkaline solution in said first step and said third step comprises injection and collision of droplets formed in an external-mix bi-fluid nozzle by mixing said alkaline solution with gas from said bi-fluid nozzle to the surface of the rotated substrate,

wherein, said alkaline solution is a mixed solution containing ammonia water, hydrogen peroxide water, and deionized water,

said acid solution supplied in said second step is an acid solution having an etching effect, said acid solution is a mixed solution containing hydrochloric acid, and hydrofluoric acid, and deionized water, and

said alkaline solution and said acid solution are both solutions at ordinary temperature,

and further comprising a rinsing step of performing rinsing by discharging deionized water to the surface of said substrate after said third step.

11. - 30. (Canceled)

31. (Previously Presented) The substrate processing method according to claim 10,

wherein said alkaline solution has a pH value of at least 11 and less than 13.